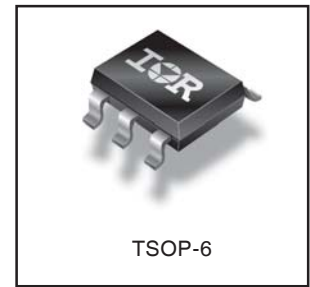
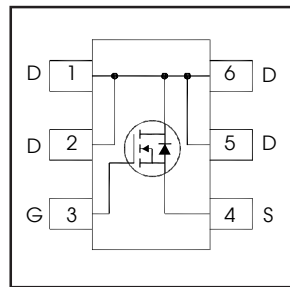


IRLTS6342PbF

HEXFET® Power MOSFET

| | | |
|--|-------------|-----------|
| V_{DS} | 30 | V |
| V_{GS} | ±12 | V |
| $R_{DS(on) \text{ max}}$ (@ $V_{GS} = 4.5V$) | 17.5 | mΩ |
| $R_{DS(on) \text{ max}}$ (@ $V_{GS} = 2.5V$) | 22.0 | mΩ |
| Q_g (typical) | 11 | nC |
| I_D (@ $T_A = 25^\circ C$) | 8.3 | A |



Applications

- System/Load Switch

Features and Benefits

Features

| |
|--|
| Industry-Standard TSOP-6 Package |
| RoHS Compliant Containing no Lead, no Bromide and no Halogen |
| MSL1, Consumer Qualification |



Resulting Benefits

| |
|----------------------------|
| Multi-Vendor Compatibility |
| Environmentally Friendlier |
| Increased Reliability |

| Orderable part number | Package Type | Standard Pack | | Note |
|-----------------------|--------------|---------------|----------|------|
| | | Form | Quantity | |
| IRLTS6342TRPBF | TSOP-6 | Tape and Reel | 3000 | |

Absolute Maximum Ratings

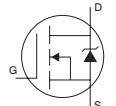
| | Parameter | Max. | Units |
|--------------------------|---|--------------|-------|
| V_{DS} | Drain-to-Source Voltage | 30 | V |
| V_{GS} | Gate-to-Source Voltage | ±12 | |
| $I_D @ T_A = 25^\circ C$ | Continuous Drain Current, $V_{GS} @ 4.5V$ | 8.3 | A |
| $I_D @ T_A = 70^\circ C$ | Continuous Drain Current, $V_{GS} @ 4.5V$ | 6.7 | |
| I_{DM} | Pulsed Drain Current ① | 64 | |
| $P_D @ T_A = 25^\circ C$ | Power Dissipation ③ | 2.0 | W |
| $P_D @ T_A = 70^\circ C$ | Power Dissipation ③ | 1.3 | |
| | Linear Derating Factor | 0.02 | W/°C |
| T_J | Operating Junction and | -55 to + 150 | °C |
| T_{STG} | Storage Temperature Range | | |

Notes ① through ④ are on page 2

Static @ T_J = 25°C (unless otherwise specified)

| | Parameter | Min. | Typ. | Max. | Units | Conditions |
|-------------------------------------|--------------------------------------|------|------|------|-------|---|
| BV _{DSS} | Drain-to-Source Breakdown Voltage | 30 | — | — | V | V _{GS} = 0V, I _D = 250μA |
| ΔBV _{DSS} /ΔT _J | Breakdown Voltage Temp. Coefficient | — | 23 | — | mV/°C | Reference to 25°C, I _D = 1mA |
| R _{DS(on)} | Static Drain-to-Source On-Resistance | — | 14.0 | 17.5 | mΩ | V _{GS} = 4.5V, I _D = 8.3A ② |
| | | — | 17.5 | 22.0 | | V _{GS} = 2.5V, I _D = 6.7A ② |
| V _{GS(th)} | Gate Threshold Voltage | 0.5 | — | 1.1 | V | V _{DS} = V _{GS} , I _D = 10μA |
| ΔV _{GS(th)} | Gate Threshold Voltage Coefficient | — | -4.3 | — | mV/°C | |
| I _{DSS} | Drain-to-Source Leakage Current | — | — | 1.0 | μA | V _{DS} = 24V, V _{GS} = 0V |
| | | — | — | 150 | | V _{DS} = 24V, V _{GS} = 0V, T _J = 125°C |
| I _{GSS} | Gate-to-Source Forward Leakage | — | — | 100 | nA | V _{GS} = 12V |
| | Gate-to-Source Reverse Leakage | — | — | -100 | | V _{GS} = -12V |
| g _{fs} | Forward Transconductance | 25 | — | — | S | V _{DS} = 10V, I _D = 6.4A |
| Q _g | Total Gate Charge | — | 11 | — | nC | V _{GS} = 4.5V |
| Q _{gs} | Gate-to-Source Charge | — | 0.5 | — | | V _{DS} = 15V |
| Q _{gd} | Gate-to-Drain Charge | — | 4.6 | — | | I _D = 6.4A |
| R _G | Gate Resistance | — | 2.2 | — | Ω | |
| t _{d(on)} | Turn-On Delay Time | — | 5.4 | — | ns | V _{DD} = 15V, V _{GS} = 4.5V ③ |
| t _r | Rise Time | — | 11 | — | | I _D = 6.4A |
| t _{d(off)} | Turn-Off Delay Time | — | 32 | — | | R _G = 6.8Ω |
| t _f | Fall Time | — | 15 | — | | See Figs. 18 |
| C _{iss} | Input Capacitance | — | 1010 | — | pF | V _{GS} = 0V |
| C _{oss} | Output Capacitance | — | 96 | — | | V _{DS} = 25V |
| C _{rss} | Reverse Transfer Capacitance | — | 70 | — | | f = 1.0MHz |

Diode Characteristics

| | Parameter | Min. | Typ. | Max. | Units | Conditions |
|-----------------|---|------|------|------|-------|--|
| I _S | Continuous Source Current (Body Diode) | — | — | 2.0 | A | MOSFET symbol showing the integral reverse p-n junction diode.  |
| I _{SM} | Pulsed Source Current (Body Diode) ① | — | — | 64 | | |
| V _{SD} | Diode Forward Voltage | — | — | 1.2 | V | T _J = 25°C, I _S = 8.3A, V _{GS} = 0V ② |
| t _{rr} | Reverse Recovery Time | — | 13 | 20 | ns | T _J = 25°C, I _F = 6.4A, V _{DD} = 24V |
| Q _{rr} | Reverse Recovery Charge | — | 5.8 | 8.7 | nC | di/dt = 100/μs ② |

Thermal Resistance

| | Parameter | Typ. | Max. | Units |
|------------------|-----------------------|------|------|-------|
| R _{θJA} | Junction-to-Ambient ③ | — | 62.5 | °C/W |

Notes:

- ① Repetitive rating; pulse width limited by max. junction temperature.
- ② Pulse width ≤ 400μs; duty cycle ≤ 2%.
- ③ When mounted on 1 inch square copper board.
- ④ R_θ is measured at T_J of approximately 90°C.

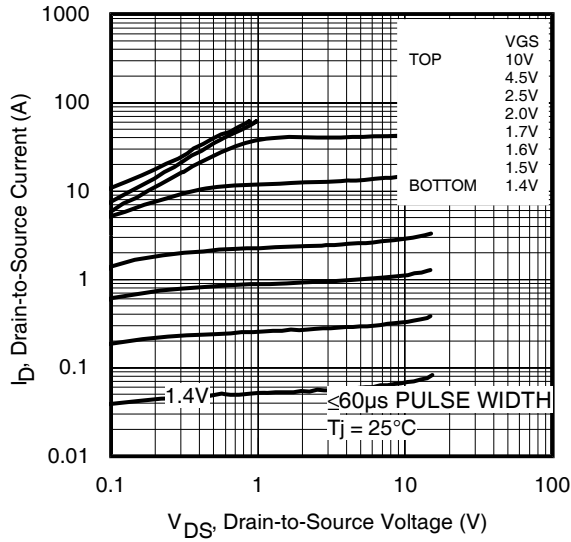


Fig 1. Typical Output Characteristics

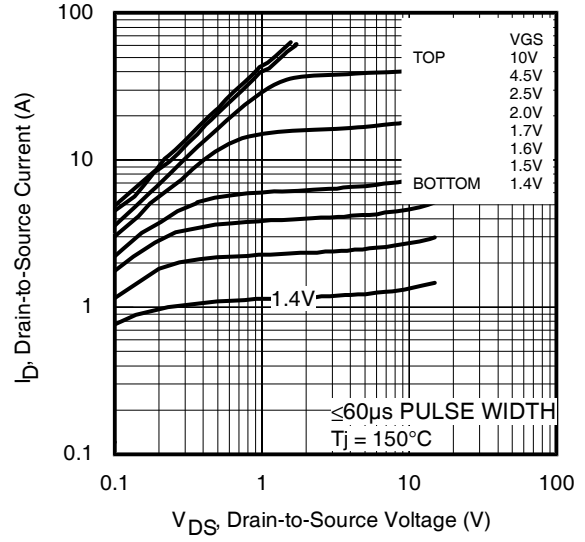


Fig 2. Typical Output Characteristics

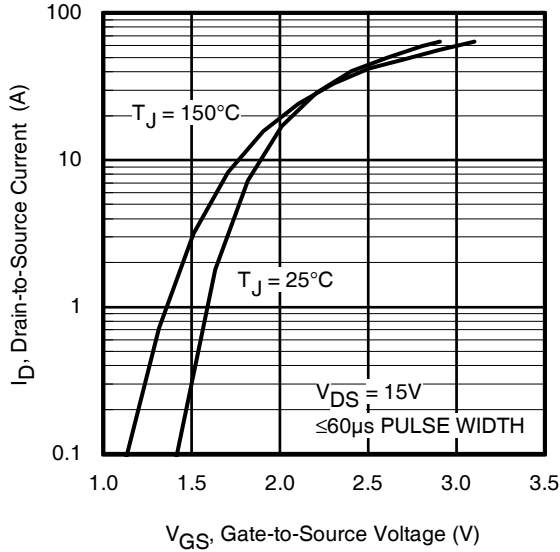


Fig 3. Typical Transfer Characteristics

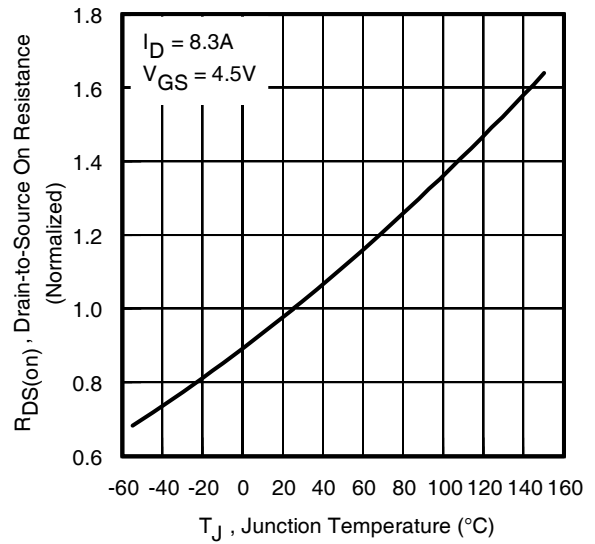


Fig 4. Normalized On-Resistance vs. Temperature

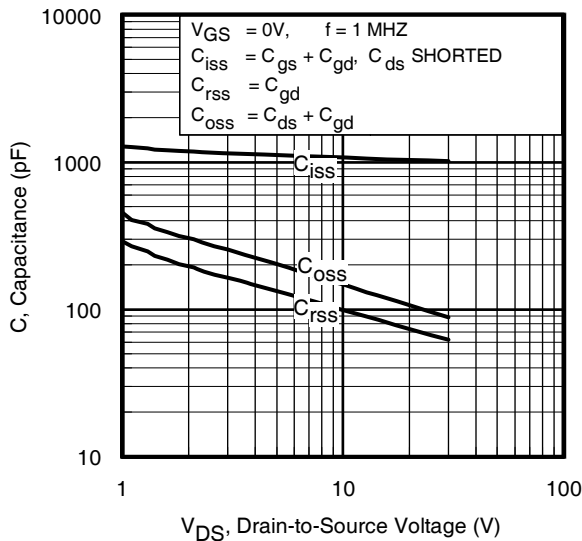


Fig 5. Typical Capacitance vs. Drain-to-Source Voltage
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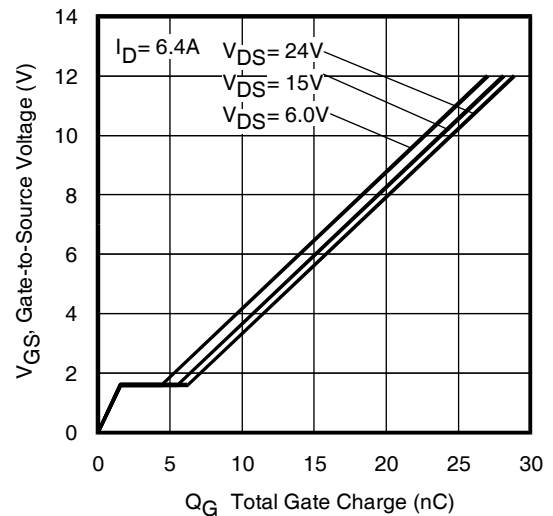


Fig 6. Typical Gate Charge vs. Gate-to-Source Voltage

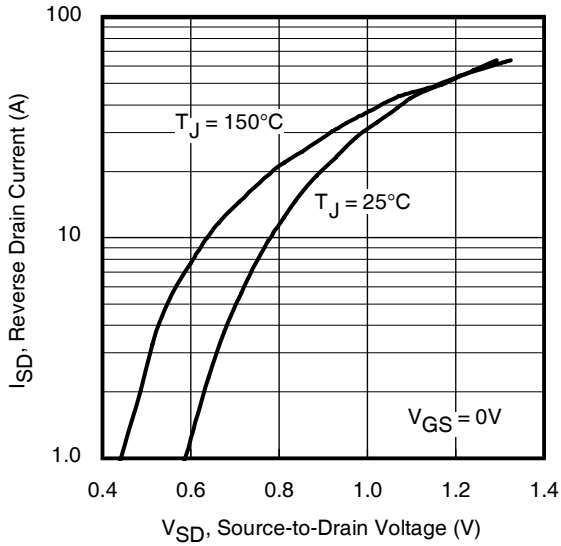


Fig 7. Typical Source-Drain Diode Forward Voltage

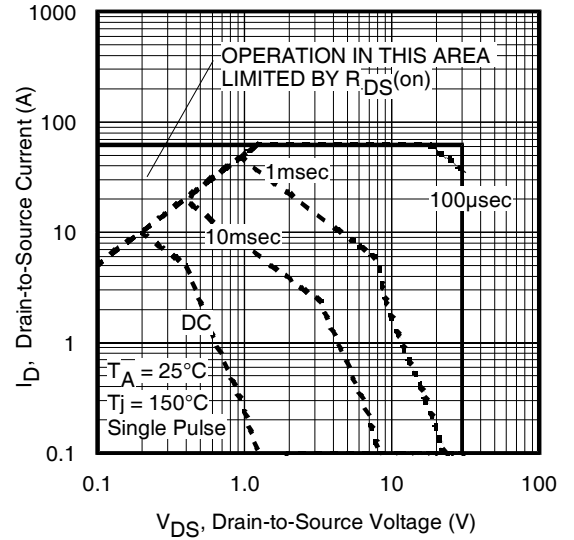


Fig 8. Maximum Safe Operating Area

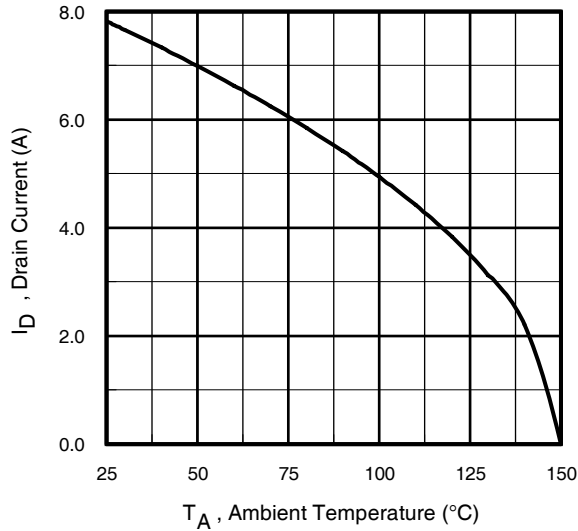


Fig 9. Maximum Drain Current vs. Ambient Temperature

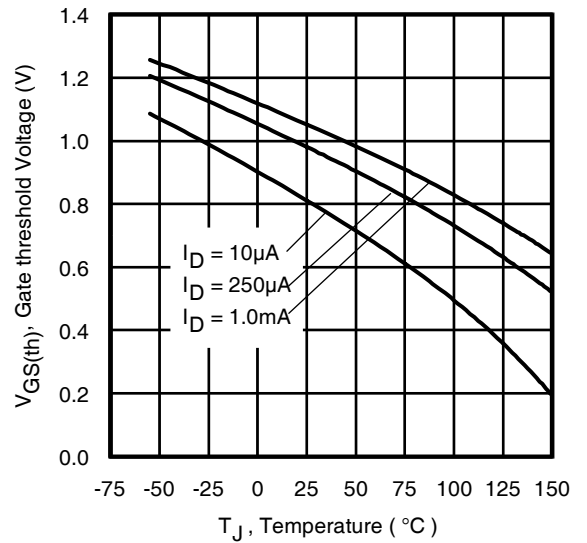


Fig 10. Threshold Voltage vs. Temperature

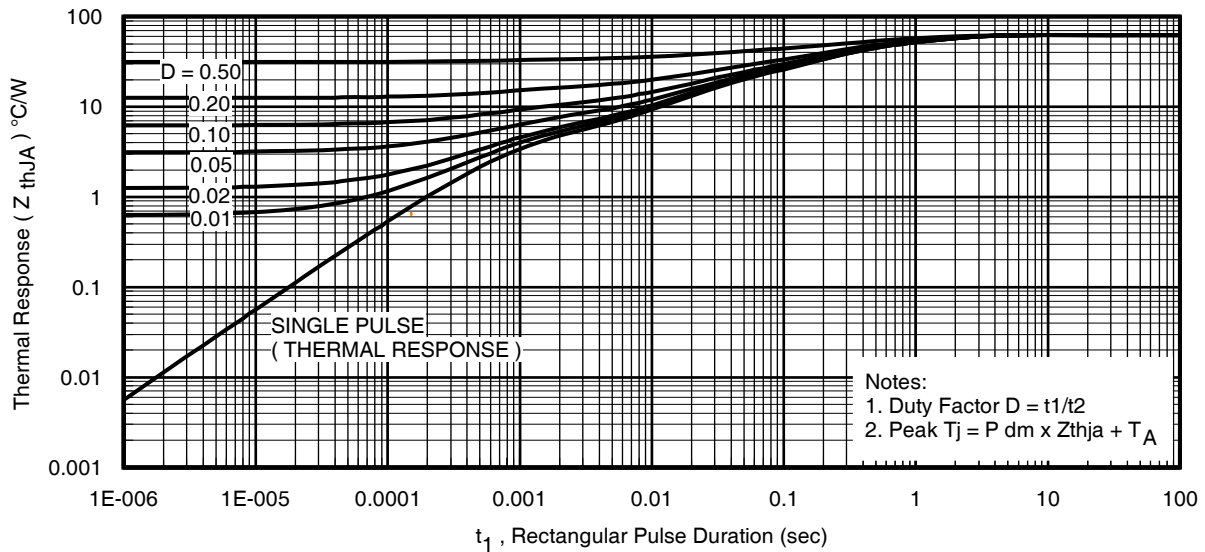


Fig 11. Maximum Effective Transient Thermal Impedance, Junction-to-Ambient

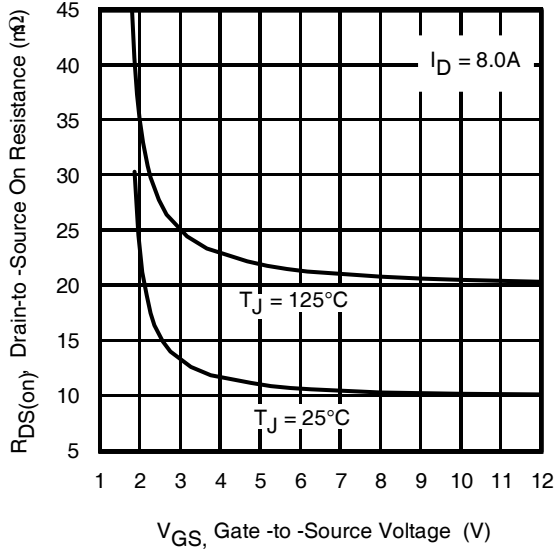


Fig 12. On-Resistance vs. Gate Voltage

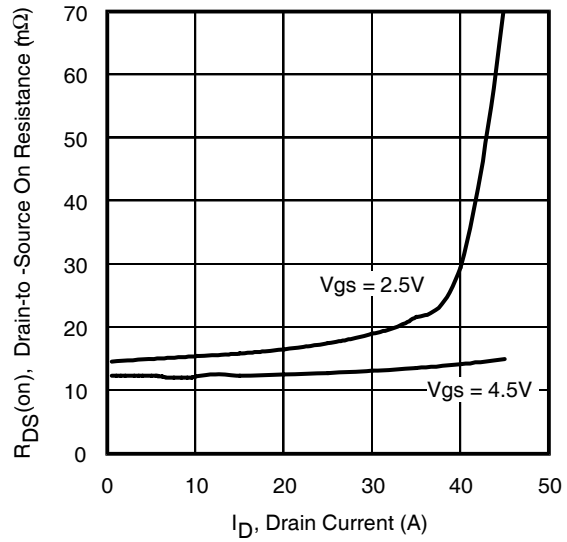


Fig 13. Typical On-Resistance vs. Drain Current

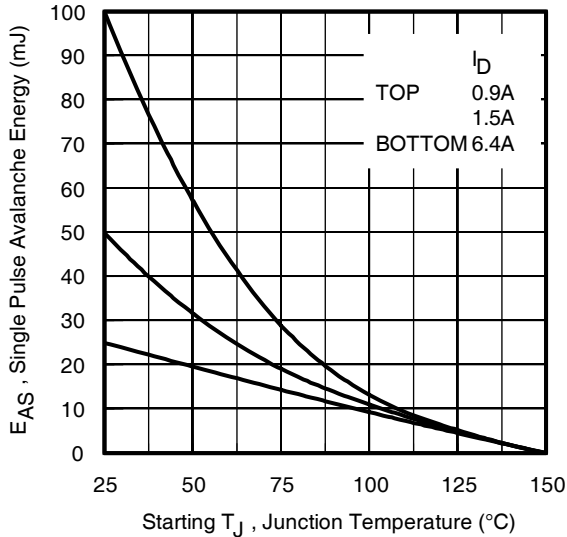


Fig 14. Maximum Avalanche Energy vs. Drain Current

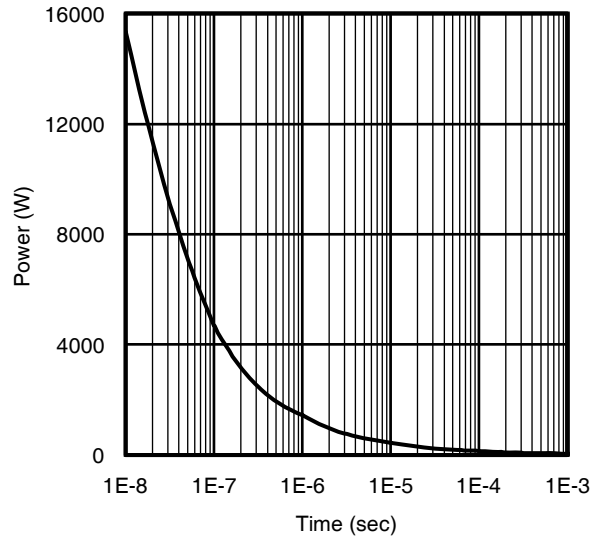
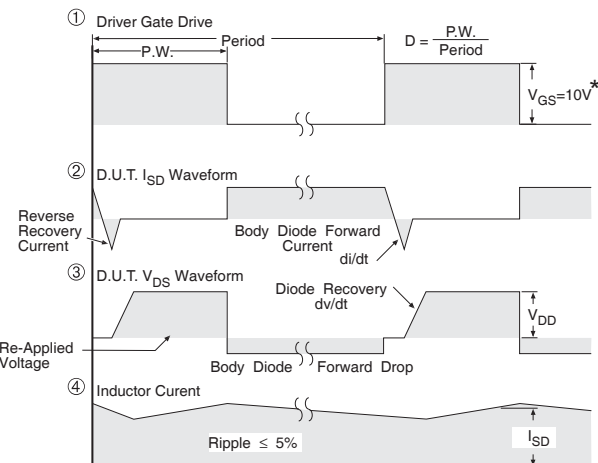
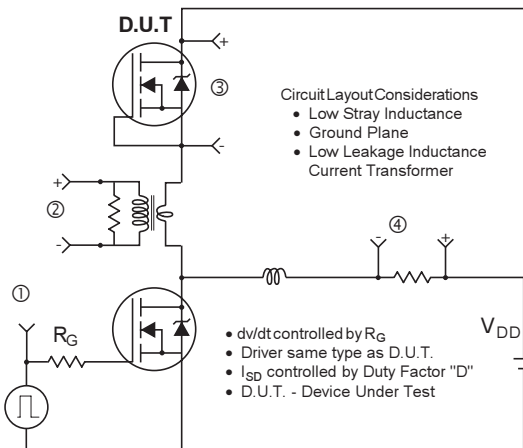


Fig 15. Typical Power vs. Time



* $V_{GS} = 5V$ for Logic Level Devices

Fig 16. Peak Diode Recovery dv/dt Test Circuit for N-Channel HEXFET® Power MOSFETs

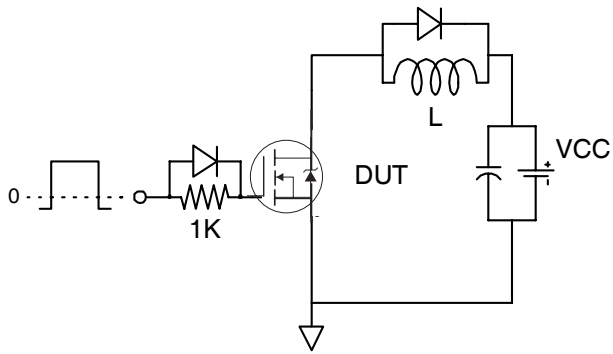


Fig 17a. Gate Charge Test Circuit

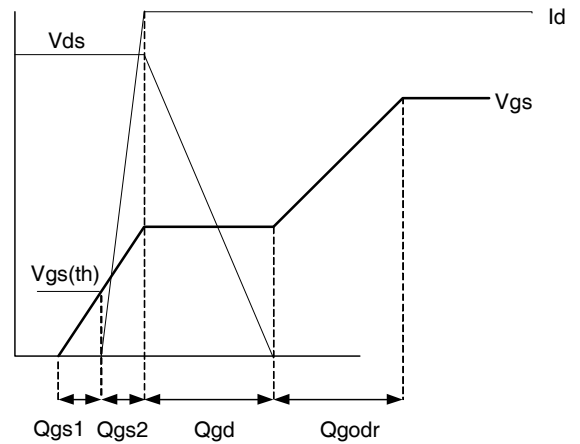


Fig 17b. Gate Charge Waveform

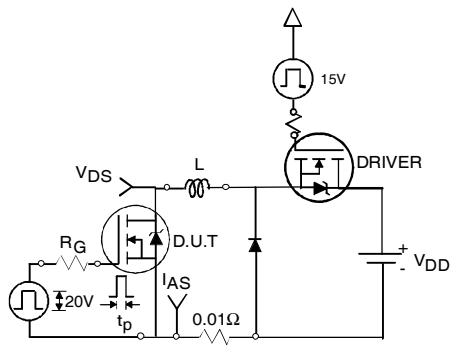


Fig 18a. Unclamped Inductive Test Circuit

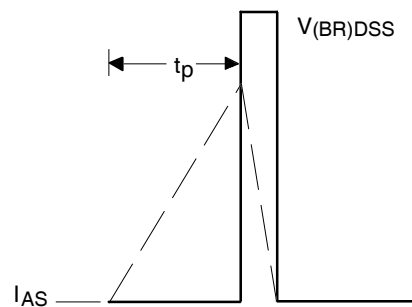


Fig 18b. Unclamped Inductive Waveforms

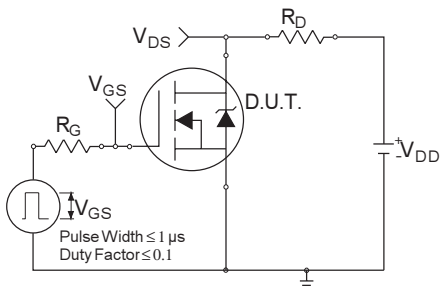


Fig 19a. Switching Time Test Circuit

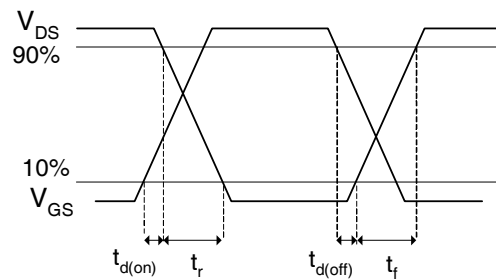
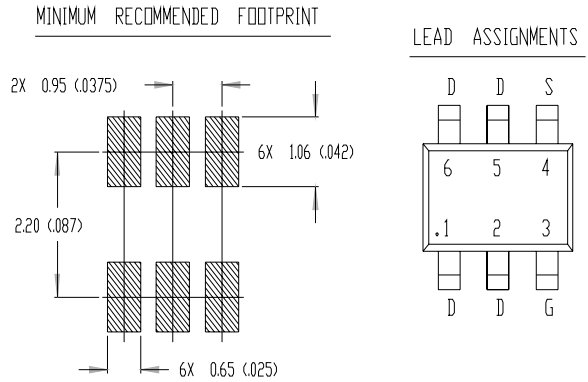
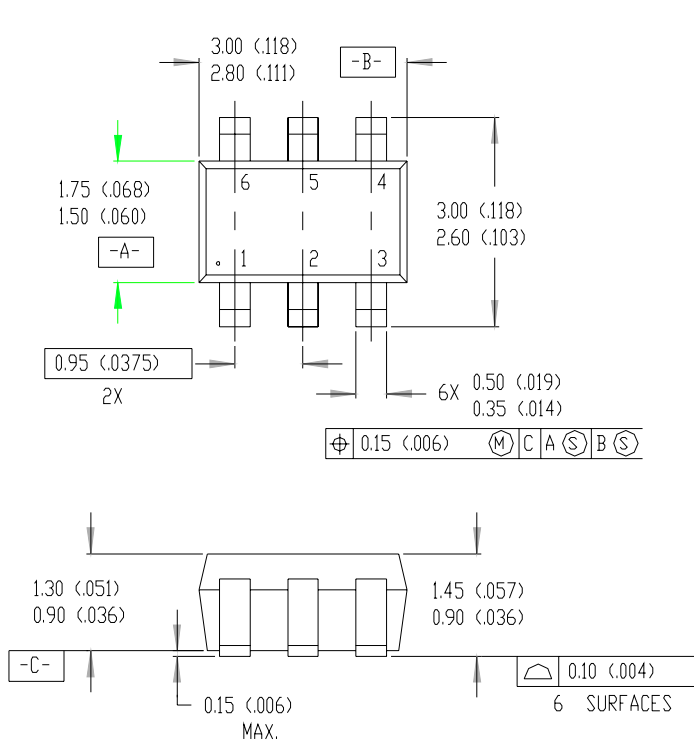
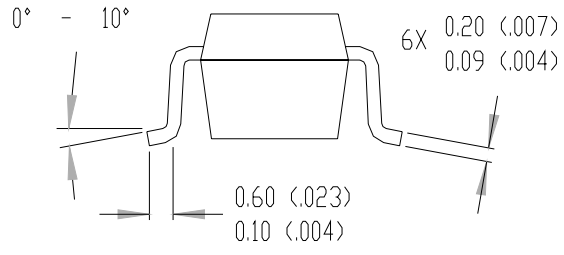


Fig 19b. Switching Time Waveforms

TSOP-6 Package Outline

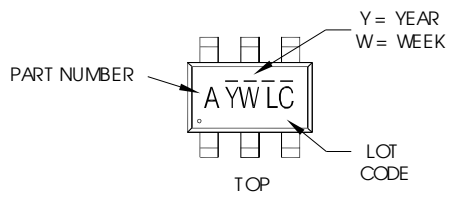


- NOTES:
1. DIMENSIONING & TOLERANCING PER ANSI Y14.5M-1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DIMENSIONS ARE SHOWN IN MILLIMETERS (INCHES).



TSOP-6 Part Marking Information

W = (1-26) IF PRECEDED BY LAST DIGIT OF CALENDAR YEAR



PART NUMBER CODE REFERENCE:

- A = SI3443DV
- B = IRF5800
- C = IRF5850
- D = IRF5851
- E = IRF5852
- F = IRF5801
- G = IRF5803
- H = IRF5804
- I = IRF5805
- J = IRF5806
- K = IRF5810
- N = IRF5802
- O = IRLTS6342TRPBF
- P = IRF58342TRPBF
- R = IRF59342TRPBF
- S = IRLTS2242TRPBF

Note: A line above the work week (as shown here) indicates Lead-Free.

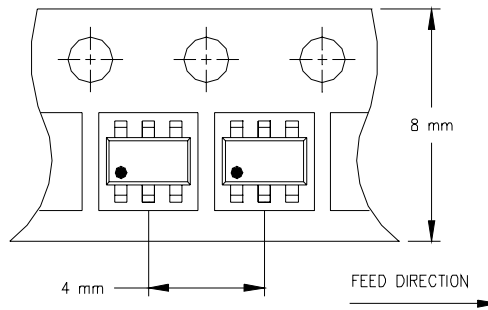
| YEAR | Y | WORK WEEK | W |
|------|---|-----------|---|
| 2001 | 1 | 01 | A |
| 2002 | 2 | 02 | B |
| 2003 | 3 | 03 | C |
| 2004 | 4 | 04 | D |
| 2005 | 5 | | |
| 2006 | 6 | | |
| 2007 | 7 | | |
| 2008 | 8 | | |
| 2009 | 9 | | |
| 2010 | 0 | 24 | X |
| | | 25 | Y |
| | | 26 | Z |

W = (27-52) IF PRECEDED BY A LETTER

| YEAR | Y | WORK WEEK | W |
|------|---|-----------|---|
| 2001 | A | 27 | A |
| 2002 | B | 28 | B |
| 2003 | C | 29 | C |
| 2004 | D | 30 | D |
| 2005 | E | | |
| 2006 | F | | |
| 2007 | G | | |
| 2008 | H | | |
| 2009 | J | | |
| 2010 | K | 50 | X |
| | | 51 | Y |
| | | 52 | Z |

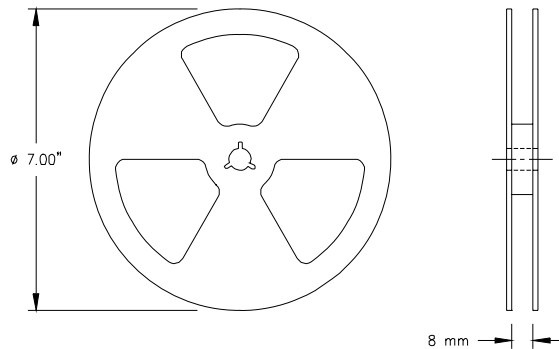
Note: For the most current drawing please refer to IR website at: <http://www.irf.com/package/>

TSOP-6 Tape & Reel Information



NOTES:

1. OUTLINE CONFORMS TO EIA-481 & EIA-541.



NOTES:

1. OUTLINE CONFORMS TO EIA-481 & EIA-541.

Qualification information[†]

| | | |
|----------------------------|---|---|
| Qualification level | Consumer ^{††} (per JEDEC JES D47F ^{†††} guidelines) | |
| Moisture Sensitivity Level | TSOP-6 | MSL 1 (per JEDEC J-STD-020D ^{†††}) |
| RoHS compliant | Yes | |

[†] Qualification standards can be found at International Rectifier's web site

<http://www.irf.com/product-info/reliability>

^{††} Higher qualification ratings may be available should the user have such requirements.

Please contact your International Rectifier sales representative for further information:

<http://www.irf.com/whoto-call/salesrep/>

^{†††} Applicable version of JEDEC standard at the time of product release.

Data and specifications subject to change without notice.

International
IR Rectifier

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